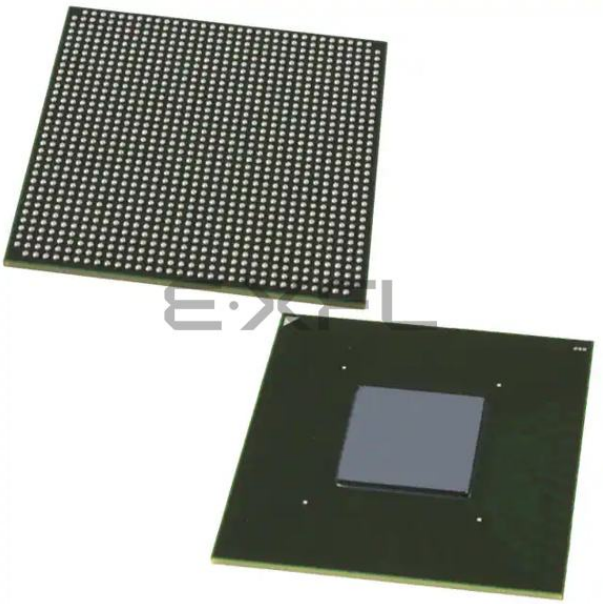

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	11460
Number of Logic Elements/Cells	242000
Total RAM Bits	15470592
Number of I/O	544
Number of Gates	-
Voltage - Supply	1.12V ~ 1.18V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA Exposed Pad
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agtfc7h3f35i3n

Symbol	Description	Minimum	Maximum	Unit
V_{CCPLL_HPS}	HPS PLL analog power supply	–0.50	3.25	V
$V_{CC\_AUX\_SHARED}$	HPS auxiliary power supply	–0.50	3.25	V
I_{OUT}	DC output current per pin	–25	40	mA
T_J	Operating junction temperature	–55	125	°C
T_{STG}	Storage temperature (no bias)	–65	150	°C

Maximum Allowed Overshoot and Undershoot Voltage

During transitions, input signals may overshoot to the voltage listed in the following table and undershoot to –2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% duty cycle.

For example, a signal that overshoots to 4.00 V can only be at 4.00 V for ~15% over the lifetime of the device; for a device lifetime of 10 years, this amounts to 1.5 years.

Table 1-2: Maximum Allowed Overshoot During Transitions for Arria V Devices

This table lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage of device lifetime.

Transceiver Power Supply Operating Conditions

Table 1-4: Transceiver Power Supply Operating Conditions for Arria V Devices

Symbol	Description	Minimum[5]	Typical	Maximum[5]	Unit
V_{CCA_GXBL}	Transceiver high voltage power (left side)	2.375	2.500	2.625	V
V_{CCA_GXBR}	Transceiver high voltage power (right side)				
V_{CCR_GXBL}	GX and SX speed grades—receiver power (left side)	1.08/1.12	1.1/1.15[6]	1.14/1.18	V
V_{CCR_GXBR}	GX and SX speed grades—receiver power (right side)				
V_{CCR_GXBL}	GT and ST speed grades—receiver power (left side)	1.17	1.20	1.23	V
V_{CCR_GXBR}	GT and ST speed grades—receiver power (right side)				
V_{CCT_GXBL}	GX and SX speed grades—transmitter power (left side)	1.08/1.12	1.1/1.15[6]	1.14/1.18	V
V_{CCT_GXBR}	GX and SX speed grades—transmitter power (right side)				
V_{CCT_GXBL}	GT and ST speed grades—transmitter power (left side)	1.17	1.20	1.23	V
V_{CCT_GXBR}	GT and ST speed grades—transmitter power (right side)				
V_{CCH_GXBL}	Transmitter output buffer power (left side)	1.425	1.500	1.575	V
V_{CCH_GXBR}	Transmitter output buffer power (right side)				

(5) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

(6) For data rate <=3.2 Gbps, connect $V_{CCR\_GXBL/R}$, $V_{CCT\_GXBL/R}$, or $V_{CCL\_GXBL/R}$ to either 1.1-V or 1.15-V power supply. For data rate >3.2 Gbps, connect $V_{CCR\_GXBL/R}$, $V_{CCT\_GXBL/R}$, or $V_{CCL\_GXBL/R}$ to a 1.15-V power supply. For details, refer to the Arria V GT, GX, ST, and SX Device Family Pin Connection Guidelines.

I/O Standard	V_{CCIO} (V)			V_{ID} (mV)[16]			$V_{ICM(DC)}$ (V)			V_{OD} (V)[17]			V_{OCM} (V)[17][18]		
	Min	Typ	Max	Min	Condition	Max	Min	Condition	Max	Min	Typ	Max	Min	Typ	Max
PCML	Transmitter, receiver, and input reference clock pins of high-speed transceivers use the PCML I/O standard. For transmitter, receiver, and reference clock I/O pin specifications, refer to Transceiver Specifications for Arria V GX and SX Devices and Transceiver Specifications for Arria V GT and ST Devices tables.														
2.5 V LVDS[19]	2.375	2.5	2.625	100	V_{CM} = 1.25 V	—	0.05	$D_{MAX} \leq$ 1.25 Gbps	1.80	0.247	—	0.6	1.125	1.25	1.375
						—	1.05	$D_{MAX} >$ 1.25 Gbps	1.55						
RSDS (HIO)[20]	2.375	2.5	2.625	100	V_{CM} = 1.25 V	—	0.25	—	1.45	0.1	0.2	0.6	0.5	1.2	1.4
Mini-LVDS (HIO)[21]	2.375	2.5	2.625	200	—	600	0.300	—	1.425	0.25	—	0.6	1	1.2	1.4
LVPECL[22]	—	—	—	300	—	—	0.60	$D_{MAX} \leq$ 700 Mbps	1.80	—	—	—	—	—	—
							1.00	$D_{MAX} >$ 700 Mbps	1.60						

Related Information

- **Transceiver Specifications for Arria V GX and SX Devices** on page 1-23
  Provides the specifications for transmitter, receiver, and reference clock I/O pin.

(16) The minimum V_{ID} value is applicable over the entire common mode range, V_{CM}.
(17) R_L range: $90 \leq R_L \leq 110\ \Omega$.
(18) This applies to default pre-emphasis setting only.
(19) For optimized LVDS receiver performance, the receiver voltage input range must be within 1.0 V to 1.6 V for data rates above 1.25 Gbps and 0 V to 1.85 V for data rates below 1.25 Gbps.
(20) For optimized RSDS receiver performance, the receiver voltage input range must be within 0.25 V to 1.45 V.
(21) For optimized Mini-LVDS receiver performance, the receiver voltage input range must be within 0.3 V to 1.425 V.
(22) For optimized LVPECL receiver performance, the receiver voltage input range must be within 0.85 V to 1.75 V for data rates above 700 Mbps and 0.45 V to 1.95 V for data rates below 700 Mbps.

High-Speed I/O Specifications

Table 1-40: High-Speed I/O Specifications for Arria V Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block. When J = 1 or 2, bypass the SERDES block.

For LVDS applications, you must use the PLLs in integer PLL mode.

The Arria V devices support the following output standards using true LVDS output buffer types on all I/O banks.

- True RSDS output standard with data rates of up to 360 Mbps
- True mini-LVDS output standard with data rates of up to 400 Mbps

Symbol		Condition	–I3, –C4			–I5, –C5			–C6			Unit
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{HSCLK_in} (input clock frequency) True Differential I/O Standards		Clock boost factor W = 1 to 40[72]	5	—	800	5	—	750	5	—	625	MHz
f_{HSCLK_in} (input clock frequency) Single-Ended I/O Standards[73]		Clock boost factor W = 1 to 40[72]	5	—	625	5	—	625	5	—	500	MHz
f_{HSCLK_in} (input clock frequency) Single-Ended I/O Standards[74]		Clock boost factor W = 1 to 40[72]	5	—	420	5	—	420	5	—	420	MHz
f_{HSCLK_OUT} (output clock frequency)		—	5	—	625[75]	5	—	625[75]	5	—	500[75]	MHz
Transmitter	True Differential I/O Standards - f_{HSDR} (data rate)	SERDES factor J =3 to 10[76]	[77]	—	1250	[77]	—	1250	[77]	—	1050	Mbps

[72] Clock boost factor (W) is the ratio between the input data rate and the input clock rate.
[73] This applies to DPA and soft-CDR modes only.
[74] This applies to non-DPA mode only.
[75] This is achieved by using the LVDS clock network.
[76] The F_{max} specification is based on the fast clock used for serial data. The interface F_{max} is also dependent on the parallel clock domain which is design dependent and requires timing analysis.
[77] The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.

Figure 1-9: SPI Master Timing Diagram

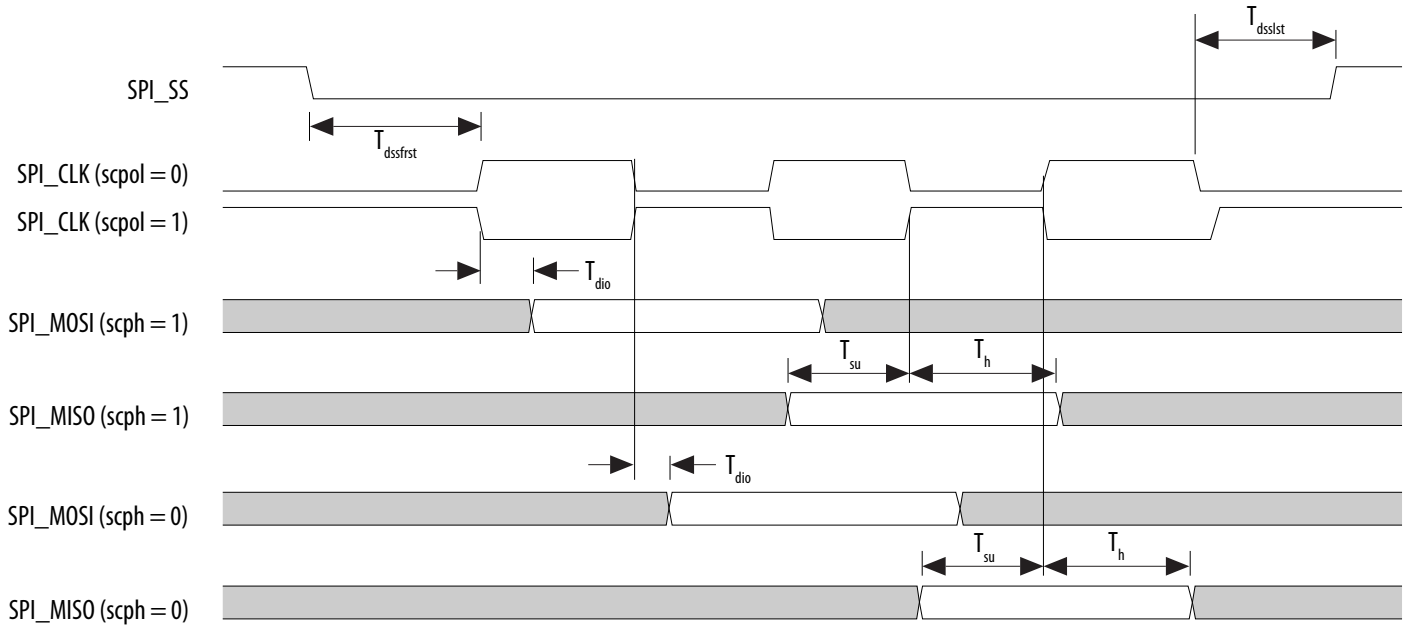


Table 1-53: SPI Slave Timing Requirements for Arria V Devices

The setup and hold times can be used for Texas Instruments SSP mode and National Semiconductor Microwire mode.

Symbol	Description	Min	Max	Unit
T_{clk}	CLK clock period	20	—	ns
T_s	MOSI Setup time	5	—	ns
T_h	MOSI Hold time	5	—	ns
T_{suss}	Setup time SPI_SS valid before first clock edge	8	—	ns
T_{hss}	Hold time SPI_SS valid after last clock edge	8	—	ns
T_d	MISO output delay	—	6	ns

Table 1-57: RGMII RX Timing Requirements for Arria V Devices

Symbol	Description	Min	Typ	Unit
T_{clk} (1000Base-T)	RX_CLK clock period	—	8	ns
T_{clk} (100Base-T)	RX_CLK clock period	—	40	ns
T_{clk} (10Base-T)	RX_CLK clock period	—	400	ns
T_{su}	RX_D/RX_CTL setup time	1	—	ns
T_h	RX_D/RX_CTL hold time	1	—	ns

Figure 1-14: RGMII RX Timing Diagram

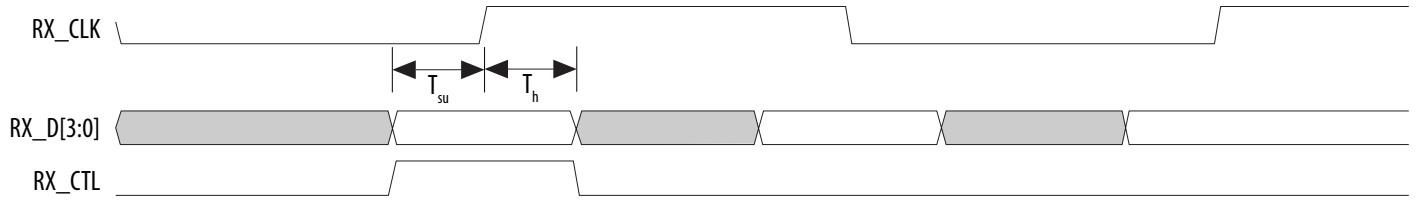
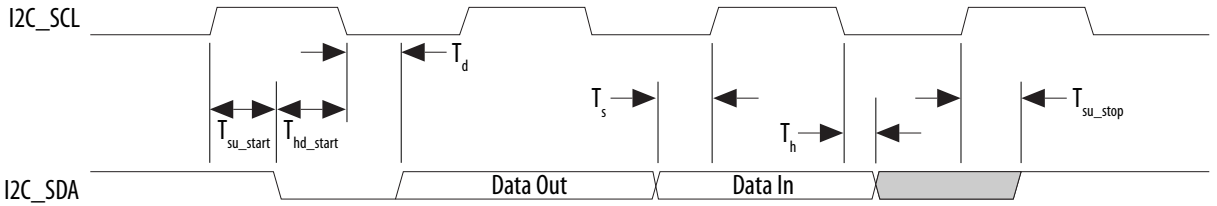


Table 1-58: Management Data Input/Output (MDIO) Timing Requirements for Arria V Devices

Symbol	Description	Min	Typ	Max	Unit
T_{clk}	MDC clock period	—	400	—	ns
T_d	MDC to MDIO output data delay	10	—	20	ns
T_s	Setup time for MDIO data	10	—	—	ns
T_h	Hold time for MDIO data	0	—	—	ns

Figure 1-16: I²C Timing Diagram



NAND Timing Characteristics

Table 1-60: NAND ONFI 1.0 Timing Requirements for Arria V Devices

The NAND controller supports Open NAND FLASH Interface (ONFI) 1.0 Mode 5 timing as well as legacy NAND devices. This table lists the requirements for ONFI 1.0 mode 5 timing. The HPS NAND controller can meet this timing by programming the C4 output of the main HPS PLL and timing registers provided in the NAND controller.

Symbol	Description	Min	Max	Unit
T_{wp} (89)	Write enable pulse width	10	—	ns
T_{wh} (89)	Write enable hold time	7	—	ns
T_{rp} (89)	Read enable pulse width	10	—	ns
T_{reh} (89)	Read enable hold time	7	—	ns
T_{clesu} (89)	Command latch enable to write enable setup time	10	—	ns
T_{cleh} (89)	Command latch enable to write enable hold time	5	—	ns
T_{cesu} (89)	Chip enable to write enable setup time	15	—	ns
T_{ceh} (89)	Chip enable to write enable hold time	5	—	ns
T_{alesu} (89)	Address latch enable to write enable setup time	10	—	ns
T_{aleh} (89)	Address latch enable to write enable hold time	5	—	ns
T_{dsu} (89)	Data to write enable setup time	10	—	ns

(89) Timing of the NAND interface is controlled through the NAND configuration registers.

Symbol	Parameter	Minimum	Maximum	Unit
t_{CF2CK}[105]	nCONFIG high to first rising edge on DCLK	1506	—	µs
t_{ST2CK}[105]	nSTATUS high to first rising edge of DCLK	2	—	µs
t_{DSU}	DATA[] setup time before rising edge on DCLK	5.5	—	ns
t_{DH}	DATA[] hold time after rising edge on DCLK	0	—	ns
t_{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
t_{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
t_{CLK}	DCLK period	$1/f_{MAX}$	—	s
f_{MAX}	DCLK frequency	—	125	MHz
t_{CD2UM}	CONF_DONE high to user mode[106]	175	437	µs
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (T_{init} \times$ CLKUSR period)	—	—
T_{init}	Number of clock cycles required for device initialization	8,576	—	Cycles

Related Information

PS Configuration Timing

Provides the PS configuration timing waveform.

(105) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

(106) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

The Quartus Prime Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete place-and-route.

Related Information

Arria V I/O Timing Spreadsheet
Provides the Arria V Excel-based I/O timing spreadsheet.

Programmable IOE Delay

Table 1-76: I/O element (IOE) Programmable Delay for Arria V Devices

Parameter[112]	Available Settings	Minimum Offset[113]	Fast Model		Slow Model					Unit
			Industrial	Commercial	–C4	–C5	–C6	–I3	–I5	
D1	32	0	0.508	0.517	0.870	1.063	1.063	0.872	1.057	ns
D3	8	0	1.763	1.795	2.999	3.496	3.571	3.031	3.643	ns
D4	32	0	0.508	0.518	0.869	1.063	1.063	1.063	1.057	ns
D5	32	0	0.508	0.517	0.870	1.063	1.063	0.872	1.057	ns

Programmable Output Buffer Delay

Table 1-77: Programmable Output Buffer Delay for Arria V Devices

This table lists the delay chain settings that control the rising and falling edge delays of the output buffer.

You can set the programmable output buffer delay in the Quartus Prime software by setting the **Output Buffer Delay Control** assignment to either positive, negative, or both edges, with the specific values stated here (in ps) for the **Output Buffer Delay** assignment.

(112) You can set this value in the Quartus Prime software by selecting **D1**, **D3**, **D4**, and **D5** in the **Assignment Name** column of **Assignment Editor**.
(113) Minimum offset does not include the intrinsic delay.

Symbol	Description	Condition	Minimum[114]	Typical	Maximum [114]	Unit
V_{CCPT}	Power supply for programmable power technology	—	1.45	1.50	1.55	V
V_{CC_AUX}	Auxiliary supply for the programmable power technology	—	2.375	2.5	2.625	V
V_{CCPD} [116]	I/O pre-driver (3.0 V) power supply	—	2.85	3.0	3.15	V
	I/O pre-driver (2.5 V) power supply	—	2.375	2.5	2.625	V
V_{CCIO}	I/O buffers (3.0 V) power supply	—	2.85	3.0	3.15	V
	I/O buffers (2.5 V) power supply	—	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply	—	1.71	1.8	1.89	V
	I/O buffers (1.5 V) power supply	—	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply	—	1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply	—	1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	—	1.14	1.2	1.26	V
V_{CCPGM}	Configuration pins (3.0 V) power supply	—	2.85	3.0	3.15	V
	Configuration pins (2.5 V) power supply	—	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	—	1.71	1.8	1.89	V
V_{CCA_FPLL}	PLL analog voltage regulator power supply	—	2.375	2.5	2.625	V
V_{CCD_FPLL}	PLL digital voltage regulator power supply	—	1.45	1.5	1.55	V
V_{CCBAT} [117]	Battery back-up power supply (For design security volatile key register)	—	1.2	—	3.0	V

(114) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

(116) V_{CCPD} must be 2.5 V when V_{CCIO} is 2.5, 1.8, 1.5, 1.35, 1.25 or 1.2 V. V_{CCPD} must be 3.0 V when V_{CCIO} is 3.0 V.

(117) If you do not use the design security feature in Arria V GZ devices, connect V_{CCBAT} to a 1.2- to 3.0-V power supply. Arria V GZ power-on-reset (POR) circuitry monitors V_{CCBAT}. Arria V GZ devices do not exit POR if V_{CCBAT} is not powered up.

Symbol	Description	Conditions	Calibration Accuracy		Unit
			C3, I3L	C4, I4	
25-Ω R_S	Internal series termination with calibration (25-Ω setting)	V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	%
50-Ω R_S	Internal series termination with calibration (50-Ω setting)	V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	%
34-Ω and 40-Ω R_S	Internal series termination with calibration (34-Ω and 40-Ω setting)	V_{CCIO} = 1.5, 1.35, 1.25, 1.2 V	±15	±15	%
48-Ω, 60-Ω, 80-Ω, and 240-Ω R_S	Internal series termination with calibration (48-Ω, 60-Ω, 80-Ω, and 240-Ω setting)	V_{CCIO} = 1.2 V	±15	±15	%
50-Ω R_T	Internal parallel termination with calibration (50-Ω setting)	V_{CCIO} = 2.5, 1.8, 1.5, 1.2 V	–10 to +40	–10 to +40	%
20-Ω, 30-Ω, 40-Ω, 60-Ω, and 120-Ω R_T	Internal parallel termination with calibration (20-Ω , 30-Ω, 40-Ω, 60-Ω, and 120-Ω setting)	V_{CCIO} = 1.5, 1.35, 1.25 V	–10 to +40	–10 to +40	%
60-Ω and 120-Ω R_T	Internal parallel termination with calibration (60-Ω and 120-Ω setting)	V_{CCIO} = 1.2	–10 to +40	–10 to +40	%
25-Ω $R_{S\_left\_shift}$	Internal left shift series termination with calibration (25-Ω $R_{S\_left\_shift}$ setting)	V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	%

Table 2-11: OCT Without Calibration Resistance Tolerance Specifications for Arria V GZ Devices

Symbol	Description	Conditions	Resistance Tolerance		Unit
			C3, I3L	C4, I4	
25-Ω R, 50-Ω R_S	Internal series termination without calibration (25-Ω setting)	V_{CCIO} = 3.0 and 2.5 V	±40	±40	%

Hot Socketing

Table 2-14: Hot Socketing Specifications for Arria V GZ Devices

Symbol	Description	Maximum
$I_{IOPIN\ (DC)}$	DC current per I/O pin	300 µA
$I_{IOPIN\ (AC)}$	AC current per I/O pin	8 mA (124)
$I_{XCVR\text{-}TX\ (DC)}$	DC current per transceiver transmitter pin	100 mA
$I_{XCVR\text{-}RX\ (DC)}$	DC current per transceiver receiver pin	50 mA

Internal Weak Pull-Up Resistor

Table 2-15: Internal Weak Pull-Up Resistor for Arria V GZ Devices

All I/O pins have an option to enable the weak pull-up resistor except the configuration, test, and JTAG pins. The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately 25 kΩ .

Symbol	Description	V_{CCIO} Conditions (V) (125)	Value (126)	Unit
R_{PU}	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if you enable the programmable pull-up resistor option.	3.0 ±5%	25	k Ω
		2.5 ±5%	25	k Ω
		1.8 ±5%	25	k Ω
		1.5 ±5%	25	kΩ
		1.35 ±5%	25	k Ω
		1.25 ±5%	25	k Ω
		1.2 ±5%	25	k Ω

(124) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{IOPIN}| = C\ dv/dt$, in which C is the I/O pin capacitance and dv/dt is the slew rate.
(125) The pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO}.
(126) These specifications are valid with a ±10% tolerance to cover changes over PVT.

I/O Standard	V_{CCIO} (V) [128]			V_{ID} (mV) [129]			$V_{ICM(DC)}$ (V)			V_{OD} (V) [130]			V_{OCM} (V) [130]		
	Min	Typ	Max	Min	Condition	Max	Min	Condition	Max	Min	Typ	Max	Min	Typ	Max
RSDS (HIO) [133]	2.375	2.5	2.625	100	V_{CM} = 1.25 V	—	0.3	—	1.4	0.1	0.2	0.6	0.5	1.2	1.4
Mini-LVDS (HIO) [134]	2.375	2.5	2.625	200	—	600	0.4	—	1.325	0.25	—	0.6	1	1.2	1.4
LVPECL [135], [136]	—	—	—	300	—	—	0.6	$D_{MAX} \leq$ 700 Mbps	1.8	—	—	—	—	—	—
	—	—	—	300	—	—	1	$D_{MAX} >$ 700 Mbps	1.6	—	—	—	—	—	—

Related Information

Glossary on page 2-73

[128] Differential inputs are powered by VCCPD which requires 2.5 V.
[129] The minimum VID value is applicable over the entire common mode range, VCM.
[130] RL range: 90 ≤ RL ≤ 110 Ω.
[133] For optimized RSDS receiver performance, the receiver voltage input range must be between 0.25 V to 1.45 V.
[134] For optimized Mini-LVDS receiver performance, the receiver voltage input range must be between 0.3 V to 1.425 V.
[135] LVPECL is only supported on dedicated clock input pins.
[136] For optimized LVPECL receiver performance, the receiver voltage input range must be between 0.85 V to 1.75 V for data rate above 700 Mbps and 0.45 V to 1.95 V for data rate below 700 Mbps.

Symbol/Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
`fixedclk` clock frequency	PCIe Receiver Detect	—	100 or 125	—	—	100 or 125	—	MHz
Reconfiguration clock (`mgmt_clk_clk`) frequency	—	100	—	125	100	—	125	MHz

Related Information

Arria V Device Overview

For more information about device ordering codes.

Receiver

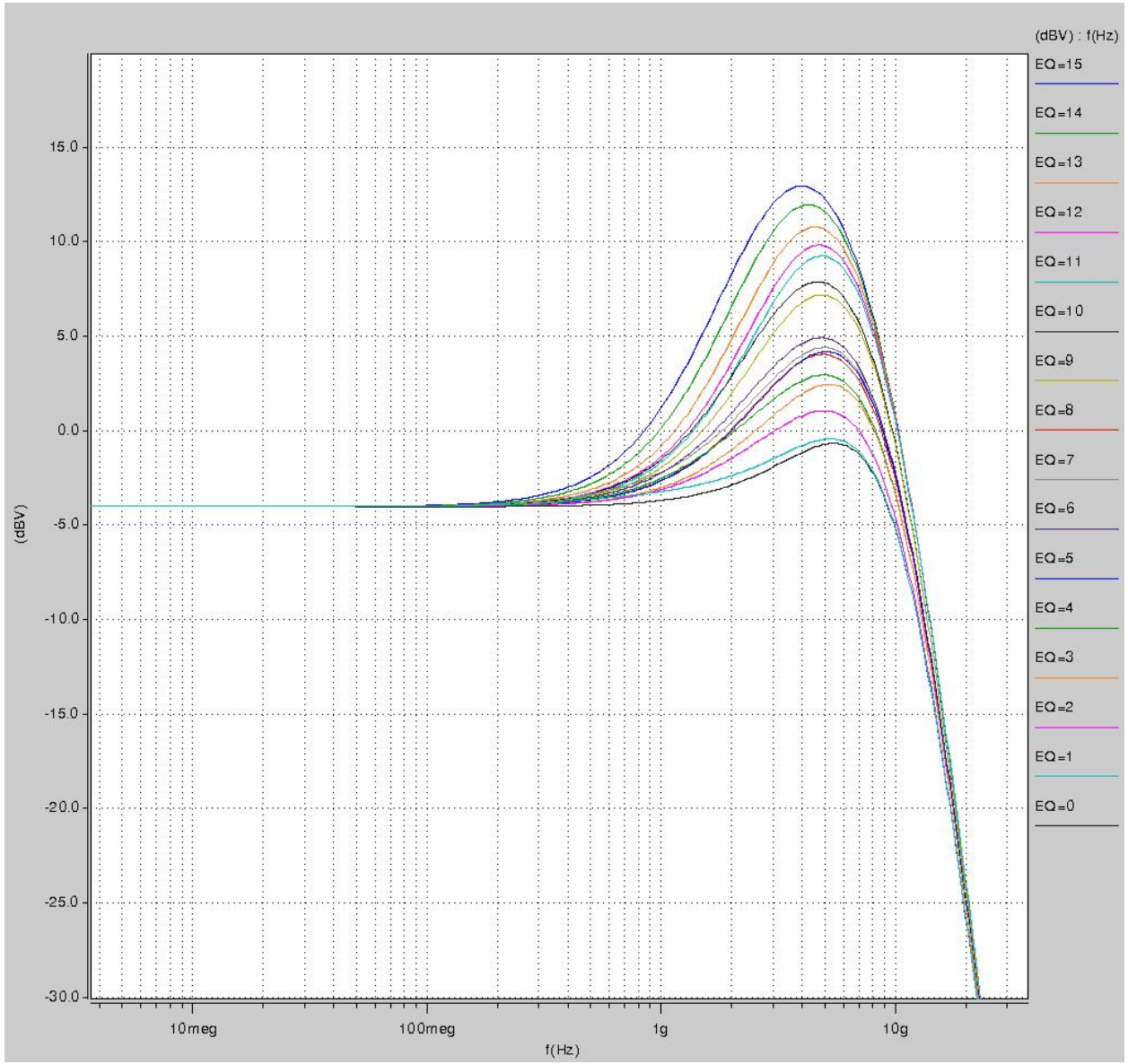
Table 2-24: Receiver Specifications for Arria V GZ Devices

Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Arria V Device Overview*.

Symbol/Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Supported I/O Standards	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS							
Data rate (Standard PCS) (143), (144)	—	600	—	9900	600	—	8800	Mbps
Data rate (10G PCS) (143), (144)	—	600	—	12500	600	—	10312.5	Mbps
Absolute V_{MAX} for a receiver pin (145)	—	—	—	1.2	—	—	1.2	V
Absolute V_{MIN} for a receiver pin	—	–0.4	—	—	–0.4	—	—	V

(143) The line data rate may be limited by PCS-FPGA interface speed grade.
(144) To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.
(145) The device cannot tolerate prolonged operation at this absolute maximum.

Figure 2-2: AC Gain Curves for Arria V GZ Channels (full bandwidth)



Symbol	Parameter	Min	Typ	Max	Unit
f_{OUT} (169)	Output frequency for an internal global or regional clock (C3, I3L speed grade)	—	—	650	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grade)	—	—	580	MHz
f_{OUT_EXT} (169)	Output frequency for an external clock output (C3, I3L speed grade)	—	—	667	MHz
	Output frequency for an external clock output (C4, I4 speed grade)	—	—	533	MHz
$t_{OUTDUTY}$	Duty cycle for a dedicated external clock output (when set to 50%)	45	50	55	%
t_{FCOMP}	External feedback clock compensation time	—	—	10	ns
$f_{DYCONFIGCLK}$	Dynamic configuration clock for `mgmt_clk` and `scanclk`	—	—	100	MHz
t_{LOCK}	Time required to lock from the end-of-device configuration or deassertion of `areset`	—	—	1	ms
t_{DLOCK}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/ delays)	—	—	1	ms
f_{CLBW}	PLL closed-loop low bandwidth	—	0.3	—	MHz
	PLL closed-loop medium bandwidth	—	1.5	—	MHz
	PLL closed-loop high bandwidth (170)	—	4	—	MHz
t_{PLL_PSERR}	Accuracy of PLL phase shift	—	—	±50	ps
t_{ARESET}	Minimum pulse width on the `areset` signal	10	—	—	ns

(169) This specification is limited by the lower of the two: I/O f_{MAX} or f_{OUT} of the PLL.
(170) High bandwidth PLL settings are not supported in external feedback mode.

DPA Mode High-Speed I/O Specifications

Table 2-42: High-Speed I/O Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.

Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
DPA run length	—	—	—	10000	—	—	10000	UI

Figure 2-3: DPA Lock Time Specification with DPA PLL Calibration Enabled

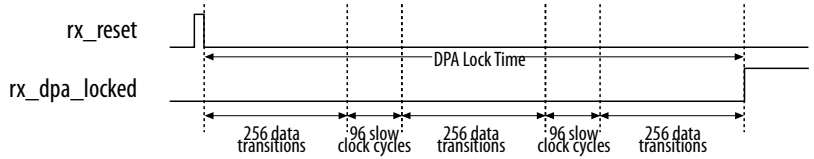


Table 2-43: DPA Lock Time Specifications for Arria V GZ Devices

The DPA lock time is for one channel.

One data transition is defined as a 0-to-1 or 1-to-0 transition.

The DPA lock time stated in this table applies to both commercial and industrial grade.

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions (201)	Maximum
SPI-4	00000000001111111111	2	128	640 data transitions

(201) This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

Symbol	Parameter	Minimum	Maximum	Unit
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (8576 × CLKUSR period) (215)	—	—

Related Information

- **DCLK-to-DATA[] Ratio (r) for FPP Configuration** on page 2-57
- **Configuration, Design Security, and Remote System Upgrades in Arria V Devices**

(215) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the "Initialization" section of the *Configuration, Design Security, and Remote System Upgrades in Arria V Devices* chapter.

Table 2-62: Uncompressed .rbf Sizes for Arria V GZ Devices

Variant	Member Code	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) (223)
Arria V GZ	E1	137,598,880	562,208
	E3	137,598,880	562,208
	E5	213,798,880	561,760
	E7	213,798,880	561,760

Table 2-63: Minimum Configuration Time Estimation for Arria V GZ Devices

Variant	Member Code	Active Serial (224)			Fast Passive Parallel (225)		
		Width	DCLK (MHz)	Min Config Time (ms)	Width	DCLK (MHz)	Min Config Time (ms)
Arria V GZ	E1	4	100	344	32	100	43
	E3	4	100	344	32	100	43
	E5	4	100	534	32	100	67
	E7	4	100	534	32	100	67

Remote System Upgrades Circuitry Timing Specification

Table 2-64: Remote System Upgrade Circuitry Timing Specifications

Parameter	Minimum	Maximum	Unit
$t_{RU\_nCONFIG}$ (226)	250	—	ns
$t_{RU\_nRSTIMER}$ (227)	250	—	ns

(223) The IOCSR **.rbf** size is specifically for the Configuration via Protocol (CvP) feature.
(224) DCLK frequency of 100 MHz using external CLKUSR.
(225) Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

Term	Definition
V_{OCM}	Output common mode voltage—The common mode of the differential signal at the transmitter.
V_{OD}	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
V_{SWING}	Differential input voltage
V_X	Input differential cross point voltage
V_{OX}	Output differential cross point voltage
W	High-speed I/O block—clock boost factor

Document Revision History

Date	Version	Changes
February 2017	2017.02.10	• Changed the minimum value for t_{CD2UMC} in the “FPP Timing Parameters for Arria V GZ Devices When the DCLK-to-DATA[] Ratio is 1” table. • Changed the minimum value for t_{CD2UMC} in the "FPP Timing Parameters for Arria V GZ Devices When the DCLK-to-DATA[] Ratio is >1" table. • Changed the minimum value for t_{CD2UMC} in the "AS Timing Parameters for AS x1 and AS x4 Configurations in Arria V GZ Devices" table. • Changed the minimum value for t_{CD2UMC} in the "PS Timing Parameters for Arria V GZ Devices" table. • Changed the minimum number of clock cycles value in the "Initialization Clock Source Option and the Maximum Frequency for Arria V GZ Devices" table.